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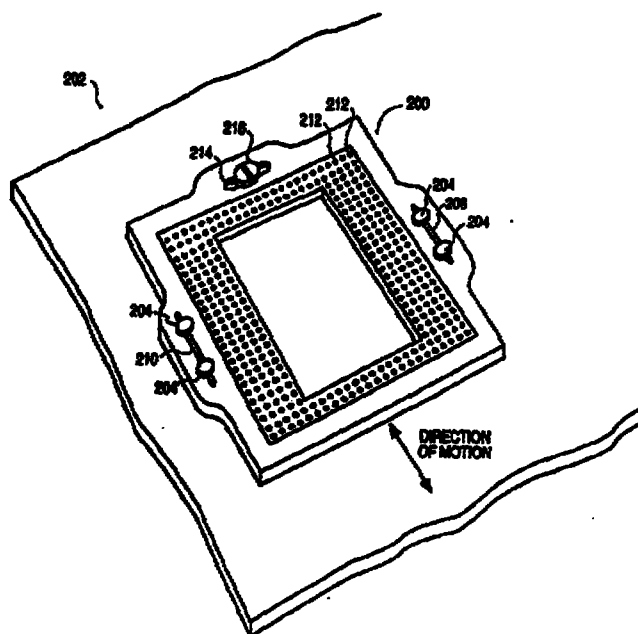
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(54) Title: LOW-PROFILE ZERO-INSERTION-FORCE SOCKET



(57) Abstract

A low-profile zero-insertion socket includes a plurality of resilient contacts (236) mounted directly into the motherboard (202). The socket has a support plate (200) slidably attached to the motherboard (202) and including a plurality of through apertures (212) formed to receive the pins (268) of a microprocessor package (266). A low-profile eccentric cam actuator (216), rotationally coupled to the motherboard (202), is provided for moving the support plate (200) that bears the microprocessor (266) to and from a position where the microprocessor pins (268) engage the resilient contacts (236).